



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): ITABASHI, et al.

Serial No.: 09/678,800

Filed: October 4, 2000

For: ELECTROLESS COPPER PLATING MACHINE THEREOF, AND
MULTI-LAYER PRINTED WIRING BOARD

Group: 2827

Examiner: T. Dinh

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

March 21, 2003

Sir:

In response to the Office Action mailed February 21, 2003, please amend the
above-identified application as follows:

IN THE CLAIMS:

Please amend the claims presently in the application as follows:

3. (Amended) An electroless copper plating method using a plating solution containing copper sulfate as copper ion sources, and a copper ion complex agent, a copper ion reducing agent, and a pH conditioner, wherein said method comprises steps of adding at least one of alkaline earth metal, alkaline earth metal oxide, alkaline earth metal hydroxide, and alkaline earth metal salt (excluding sulfuric salt) into said plating solution, reacting with and precipitating sulfuric ions as an alkaline earth metal salt, measuring the concentration of sulfuric ions in said plating solution, and regulating the concentration thereof to a preset optimum concentration during

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